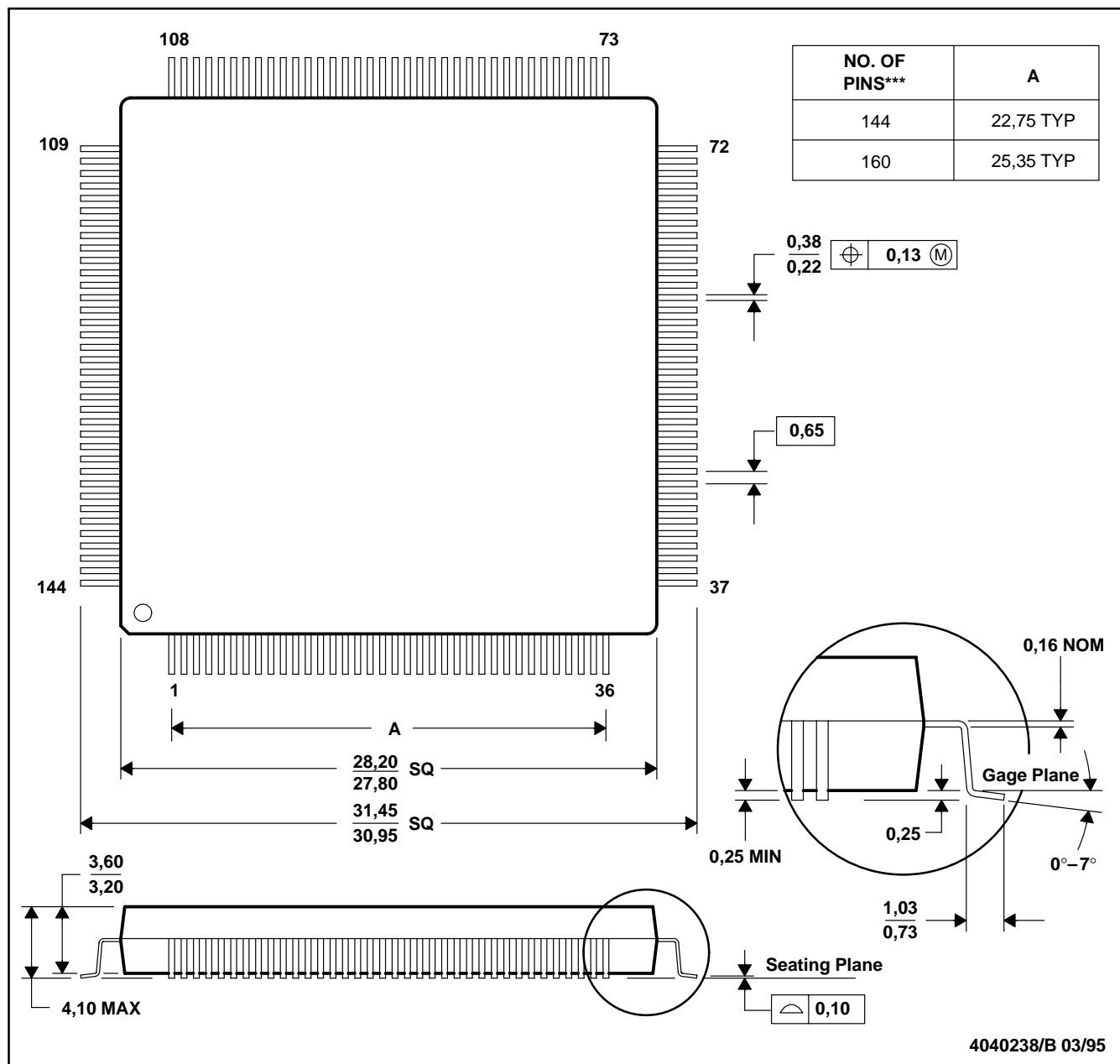


## PLASTIC QUAD FLATPACK (DIE-DOWN)

144 PIN SHOWN



- NOTES: A. All linear dimensions are in millimeters.  
B. This drawing is subject to change without notice.  
C. Thermally enhanced molded plastic package with a heat spreader (HSP)  
D. Falls within JEDEC MS-022  
E. The 144 PCD is identical to the 160 PCD except that four leads per corner are removed.

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